ASML

Virtual overlay metrology for fault detection supported with integrated metrology and machine learning

Emil Schmitt-Weaver

Introduction

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Public

Slide 2

- All wafers moving though a lithocluster get measured with TWINSCAN metrology
- Some wafers leaving the lithocluster get measured with Integrated Metrology



Integrated Metrology

Integrated Metrology

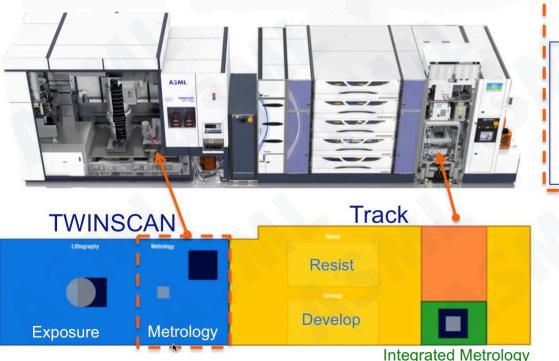
Introduction

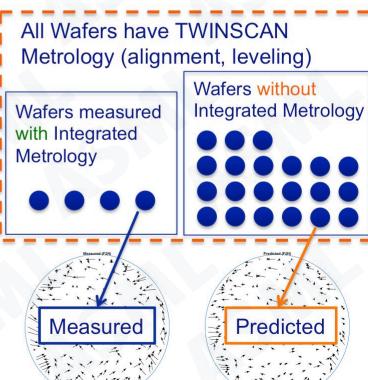
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Public Slide 3

Our study explores the use of a regression based machine learning technique, known as "function approximation" to predict overlay

behavior for all of the wafers within a lot







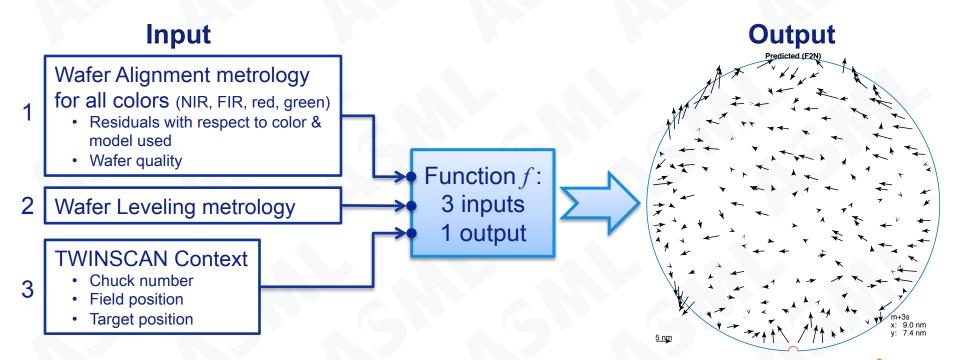
- Introduction
- How the function works
- Data separation into Training and Testing groups
- Training with Bayesian Automated Regularization
- Prediction Vs. Measured Overlay as regression plots
- Precision of Trained Function as a vector map
- Results
- Conclusion

How the function works



Public Slide 5

Function input comes from TWINSCAN metrology & context;







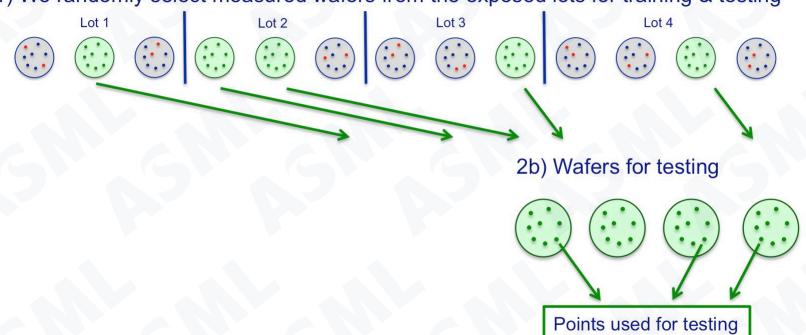
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Data separation into Training and Testing groups

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Public Slide 7

1) We randomly select measured wafers from the exposed lots for training & testing

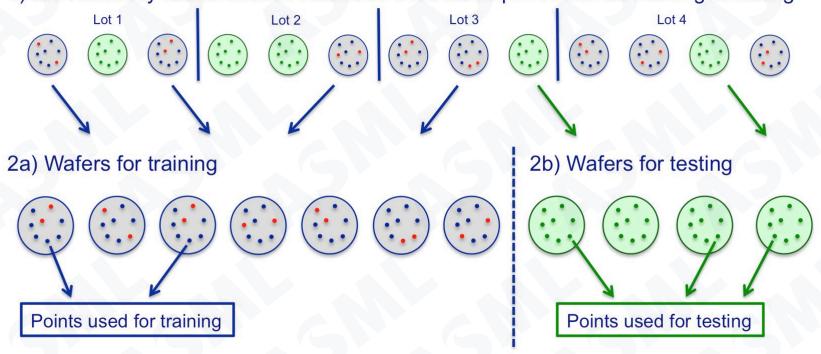


Data separation into Training and Testing groups



Public Slide 8

1) We randomly select measured wafers from the exposed lots for training & testing

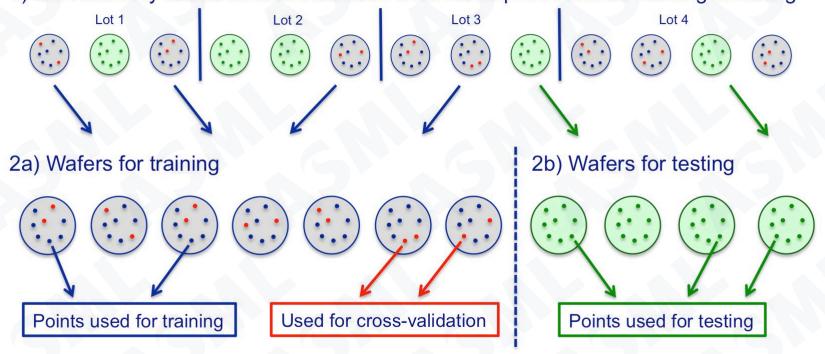


Data separation into Training and Testing groups



Public Slide 9

1) We randomly select measured wafers from the exposed lots for training & testing





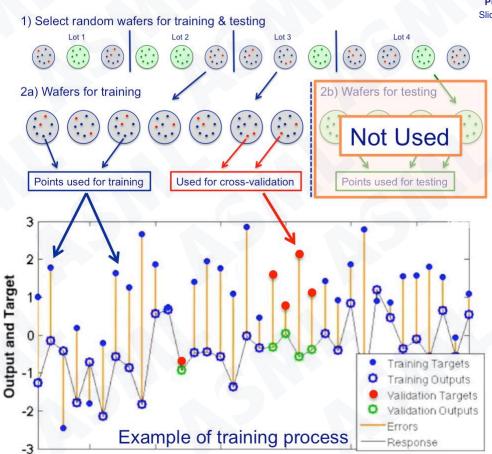
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Training with Bayesian Automated Regularization

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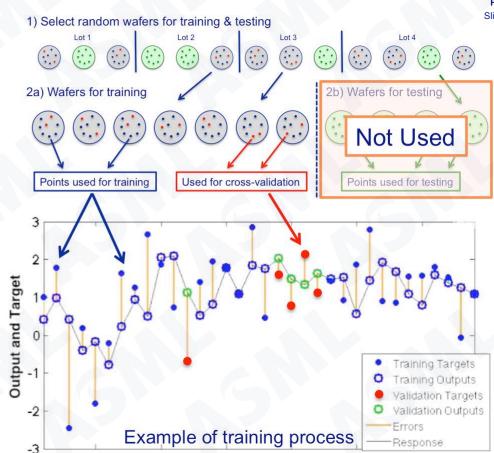
 To reduce the likelihood of overfitting the training dataset, a Bayesian framework with automated regularization is employed



Training with Bayesian Automated Regularization

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- To reduce the likelihood of overfitting the training dataset, a Bayesian framework with automated regularization is employed
- The training process repeats in cycles until convergence, which is when the sum-squared error, the sum squared weights, and the effective number of parameters reach a constant value or till the cycle limit is reached
- If the cycle limit is reached before convergence a new random sample of points is selected for <u>training</u> and <u>cross-validation</u> points within the training dataset, while starting iterations toward convergence where the previous cycle stopped



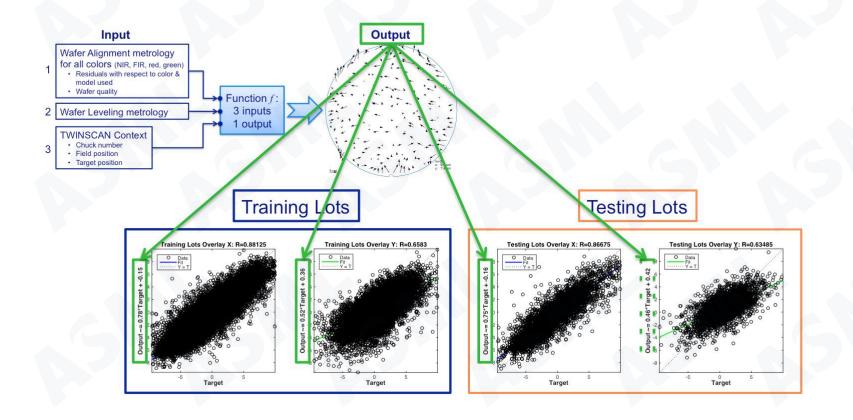


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Point-to-point correlation between the functions predicted Output vs. Measured

Public Slide 14

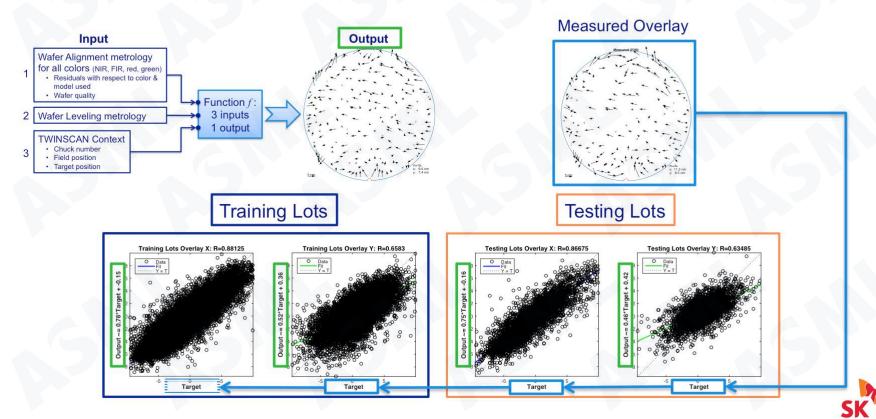




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Point-to-point correlation between the functions predicted Output vs. Measured

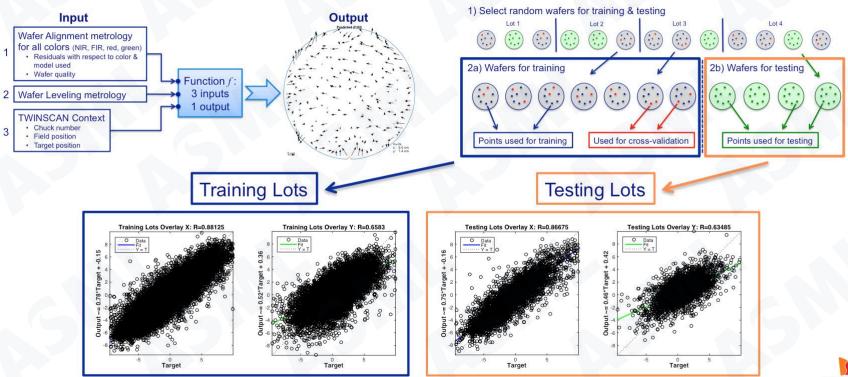
Public Slide 15





Public Slide 16

- Point-to-point correlation between the functions predicted Output vs. Measured
- Wafers from both the Training and Testing Groups are used



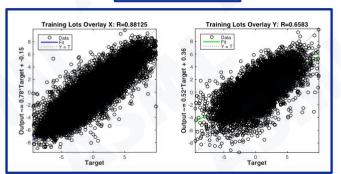


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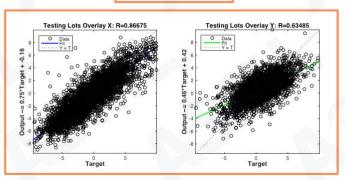
Slide 17

- Because the Testing group of wafers are "blind" to the training process we can use R-values to judge the performance of the trained function.
- R-values of the testing wafers ≈ to the R-values of the training wafers.
 - Overlay X (0.88) and Y (0.66) of the training wafers
 - Overlay X (0.87) and Y (0.63) of the testing wafers
- From this we conclude that the network generalized well with the automated regularization algorithm.

Training Lots



Testing Lots





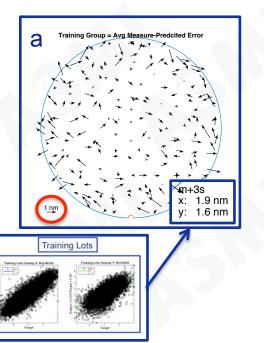


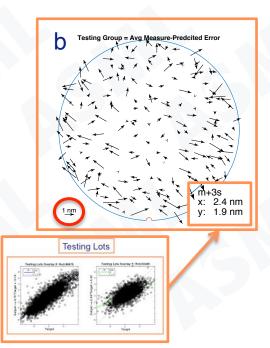
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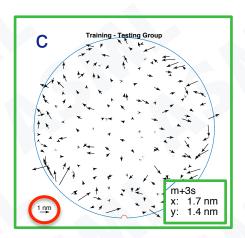
Precision of Trained Function as a vector map

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- Noise between the measured and predicted overlay is relatively consistent for both Training and Testing groups
- Consider the error as a plus or minus contribution per wafer coordinate position of any prediction from the trained function







Point - Point delta between a) and b)



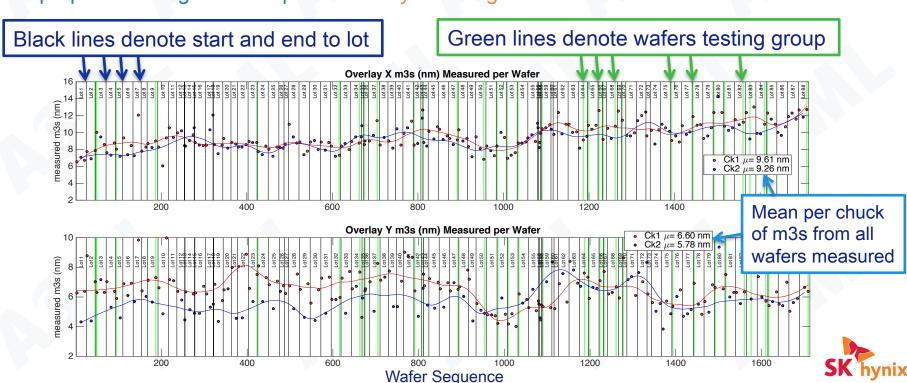


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Results – Measured Data

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- SK hynix provided the on product overlay data for our proof book analysis.
- Process for the 20nm DRAM layer was intentionally manipulated as it was prepared for high volume production by the integration team



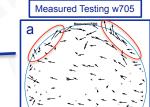
Results – Overlay X

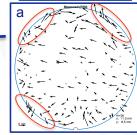


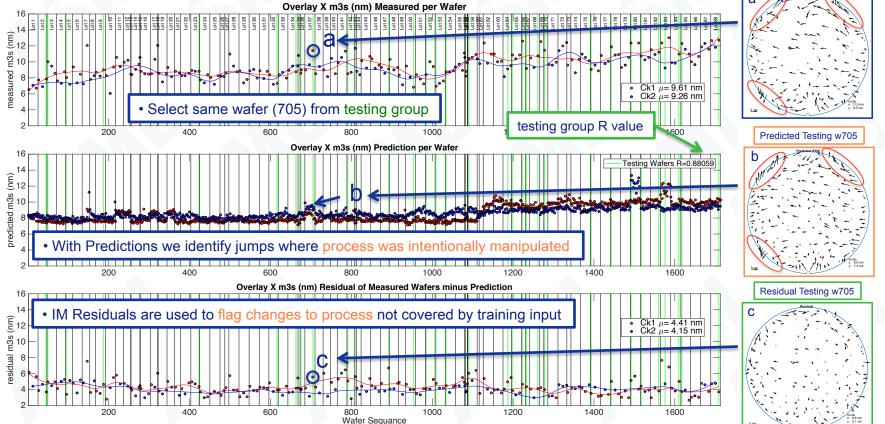


Slide 22

Measured, Predicted & Residual Integrated Metrology (IM)







Results – Overlay Y

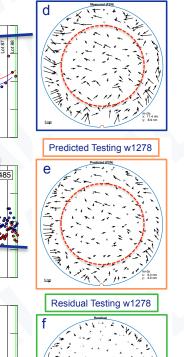


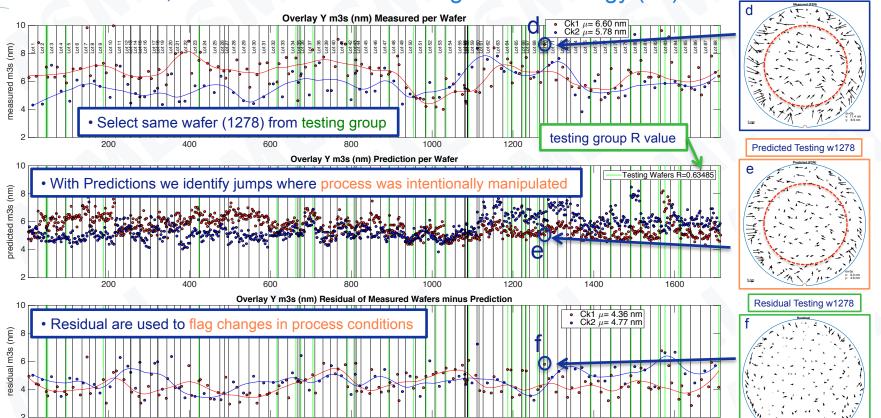
Measured Testing w1278



Slide 23

Measured, Predicted & Residual Integrated Metrology (IM)





1000

Wafer Sequance

1400



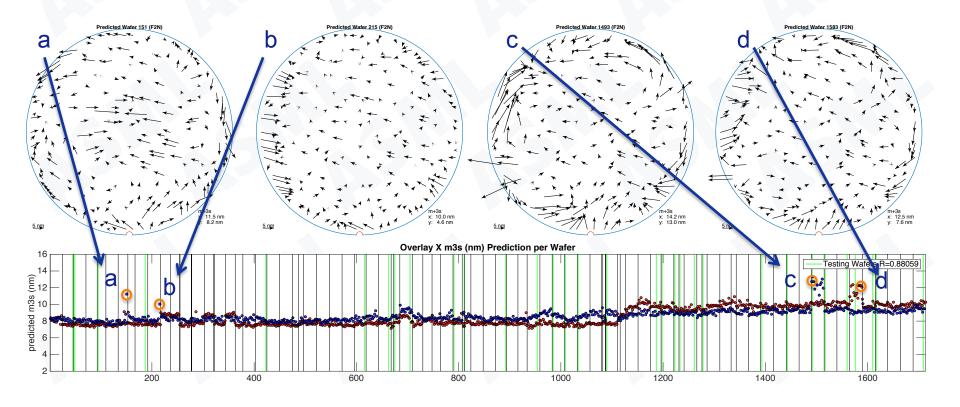
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Conclusion 1

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 With the Predictions we identify jumps in the overlay data where process was intentionally manipulated by the integration team



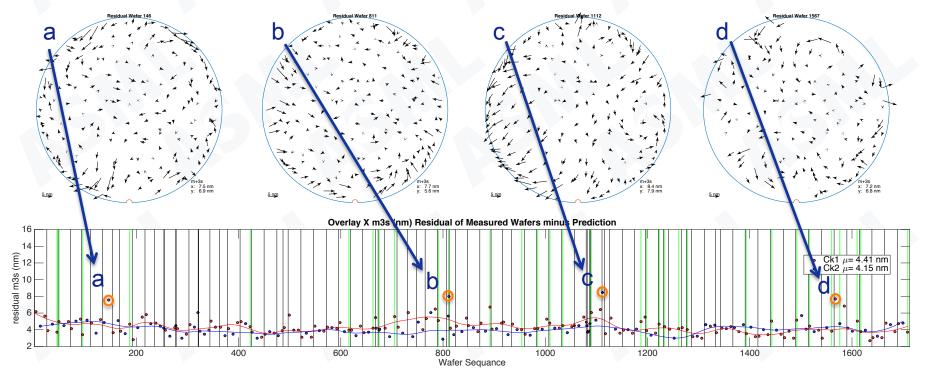


Conclusion 2

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- With Residuals we flag wafers from IM.
 - Something other then inputs we trained with is effecting the overlay signature
 - This can be used to remove a wafer from APC or to trigger an investigation



Moving forward



- Work on this subject is open to users with interest in exploring the application, both in production and development environments
- Topics of interest include exploring effect;
 - Fab context from outside the lithocluster has on the overlay prediction
 - Increasing the number of parallel works and neurons has toward improving the R value (correlation coefficient) between the predicted output and target values in the testing dataset

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